

Elephantech

1st and only mass-producer of inkjet-printed circuit boards making the world sustainable











What's PCBs



Essentials for anything electrified





\$90bn market & CAGR 6%



Problems

High environmental impact



66M t-CO2eq

0.13 % of global emissions

2x bigger than the semiconductor foundry



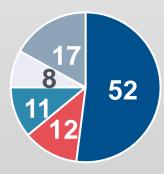
4M m³ of wastewater generated

High concentration of hydrochronic acid

Geopolitical Risk

PCBs: Highly dependent on

China



China

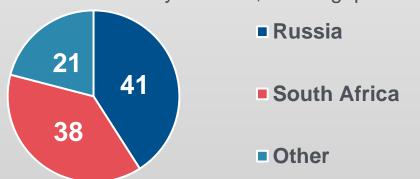
Taiwan

South Korea

Japan

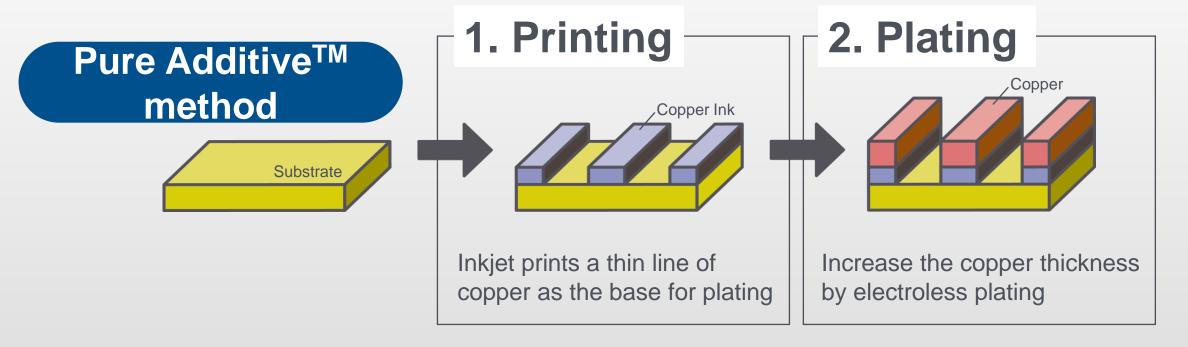
Other





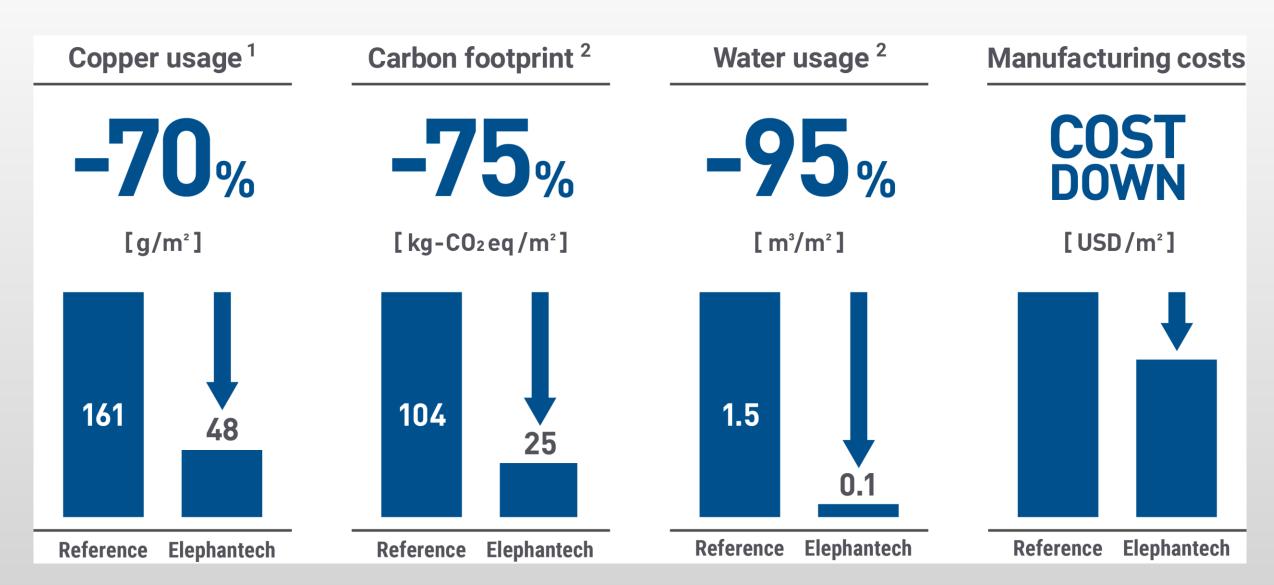


Pure Additive[™] method – Print only where necessary



Subtractive method

Make it sustainable without costing additional





Process is simple & easy to implement



Very light wastewater treatment facilities

Small equipment footprint

Equivalent productivity

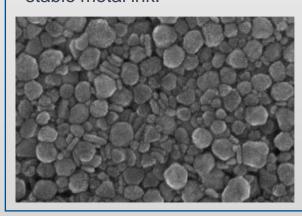
No chemical etching: Palladium Free

Vertically integrated technologies – From copper to PCB



NanoparticleSynthesis

Our process yields small and uniform copper nanoparticles essential to the production of stable metal ink.



2 Metal Ink Formulation

We convert the nanoparticles into a stable metal ink that is optimized for inkjet printing with a long shelf life.



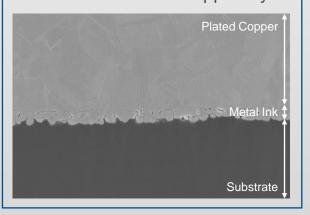
3 Metal Inkjet Printing

Our proprietary machinery and printhead control system enables precise inkjet printing of metal ink.



4 Electroless Plating

Our advanced high-speed electroless copper plating technology effectively enhances the thickness of the copper layer.



79 patents applied and 1740 internal technical reports published¹



Our factory in Aichi, Japan for mass production

9 years since foundation

50M USD

fundraised

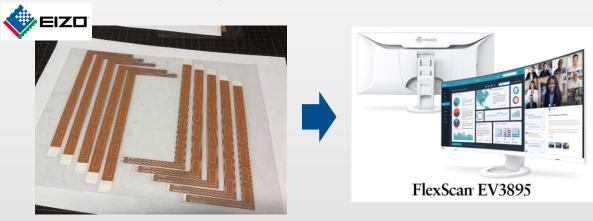
Mass-production

is successfully ongoing

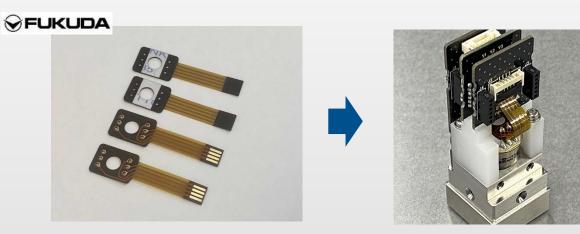


Mass production examples

EIZO – Display switches



Fukuda – Pressure Sensor Module



Starting confidential multi-million scale mass-production for Europe customers

Great quality. Certificated.

Quality tests

- ✓ Flex strength test (Sliding test)
- √ Flex strength test (MIT test)
- ✓ Bending resistance test
- ✓ High temperature storage test
- ✓ Highly accelerated stress test (HAST)
- ✓ Low temperature storage test
- ✓ High temperature exposure test
- ✓ Chemical durability test
- ✓ Ion-migration test
- ✓ Surface layer withstand voltage test
- ✓ Thermal shock test
- ✓ Peel strength test
- → More details in the Appendix

Certificates

- ✓ ISO9001:2015
- ✓ ISO14001:2015
- ✓ UL94 V-0



Compliance

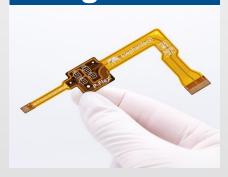
✓ RoHS

Improving product specifications and developing Inkjet system while expanding sales worldwide.

2023~2024

2025

Single side





Double side





Double side









We would like to

Meet with potential customers/business partners who are interested in our technology and considering implementing it.



Meet with investors for the next round of funding.

Elephantech



We are rapidly deploying our sustainable PCBs

2023 2025 **10K** m² **200K** m² Single-sided Call for Production capacity Production capacity Flexible reservations Circuits 30% reserved¹ Nagoya Plant (2020~) Call for **Double-sided** 1 M m² Next plant launch **Flexible** 2025~ Production capacity customers Circuits Call for

Double-sided Rigid PCB

Next plant 2025~

1M m² Production capacity

Call for launch customers

Also planning to sell the printers and to develop multilayers



Strategic business partners and shareholders

Strategic business partners



Partnership on inkjet printing technology



Mass production support and material supply



International marketing and sales



Co-development of IMPC®



Material supply

Other shareholders









... and more



We are the only one replacing existing PCBs

Startups







- Not yet mass-producing (Mass-producing) is challenging for startups)
- Not really trying to replace existing PCBs (because it's unattractive to VCs)

Incumbents







- Incumbent PCB manufactures generally have neither material nor equipment technology.
- No capability, no motivation to disrupt the existing industry.



- Committed to replace existing PCBs with a low-carbon alternative
- Already mass-producing and used for electronics manufacturing

Leadership team

Founders



Shinya Shimizu
Co-Founder / Managing Director / CEO & CTO



Satoshi Konagai COO / General Manager, Sales



Hiroaki Nasu General Manager, Engineering



Management Team

Naohiro Hirata
General Manager,
Manufacturing



Keita Sakimura
General Manager,
Corporate



Keisuke Ito General Manager, CEO office



Masaaki Sugimoto Co-Founder / Director / SVP

Independent Directors



Tomihisa Kamada



Kengo Ueha



Masahiro Sameshima

Corporate Auditor



Kazuhiko Noda

Key characteristics – Pure Additive™ method



Minimal process required

Just inkjet printing and metal plating – neither etching nor exposure processes are required.

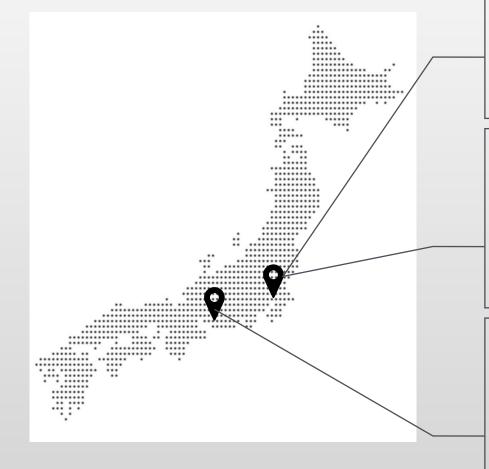
Environment Friendly

The Pure Additive[™] method reduces carbon footprint by 75% and water usage by 95%.

Reliable Printed Circuit Boards

The Pure Additive[™] method has been in mass production for several years and our products are commercially used.

Locations





Hatchobori office

Headquarters and prototyping plant 4-3-8 Hatchobori, Chuo, Tokyo 104-0032, Japan



Shinkiba R&D center

R&D of materials and the inkjet printing system 1-3-14 Shinkiba, Koto, Tokyo 136-0082, Japan

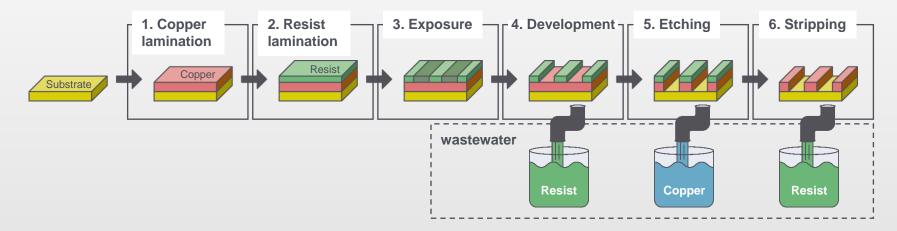


AMC Nagoya

Additive Manufacturing Center/Mass production plant 2-1 Tango-dori, Minami, Nagoya, Aichi 457-0801, Japan (Located in Mitsui Chemcals Inc. Nagoya Works)

The PCB industry poses huge environmental impacts

Subtractive method: a Wasteful standard of printed circuit boards production



1. Greenhouse Gas Emissions



66M t-CO2eq, 0.13% of global emissions¹

2x bigger than the semiconductor foundry²

10% of emissions from Apple's manufacturing³

\$4.4B of potential carbon costs⁴

2. Wastewater Pollution



4M m³ of wastewater generated⁵

140,000 tons of copper contained

10~15 wt% of copper concentration

High concentration of hydrochronic acid



^{*}All data shown in the chart are numbers per year

^{1.} Data of 2016, 100%=49.4bn t CO2eg; Our World in Data

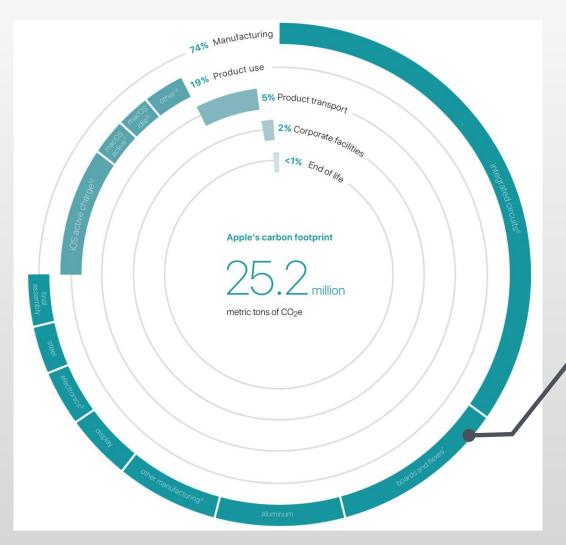
^{2.} Excluding downstream(cradle-to-gate), Printed Circuit Board: 0.1t/m² from AT&S report, multiplied by 4.4T m² global market. Semiconductor Foundry: Estimated from TSMC, 16.2 Mt, divided by its share of 55%.

^{3.} Apple - Environmental Responsibility Report 2019

^{4.} Assuming \$100/t-CO2 ea

^{5.} Recovery of copper from printed circuit board (PCB) acidic etching wastewater: Ammonia regulates the crystallization of high valued copper salt (2022)

10% of Apple's manufacturing emission comes from bare PCBs



"In 2020, we've made clear gains with our work on integrated circuits and boards and flexes—components we've prioritized because they are carbon-intensive."

Apple Environmental Progress Report 2021

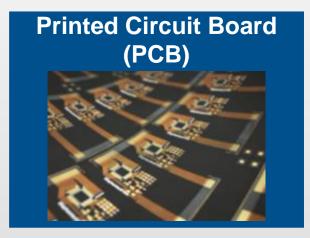
10% of total manufacturing carbon footprint comes from boards and flexes

Source: Apple Environmental Responsibility Report 2019

Introducing a versatile technology: metal nanoparticle inkjet printing for a variety of applications, starting with PCB production

Elephantech Core business

Potential metal inkjet printing applications



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- \$90bn market growing with 6% CAGR
- Essential for anything electrified (e.g., Smartphones, PC, Automotives)
- Responsible for 0.1% of total greenhouse gas(GHG) emissions





